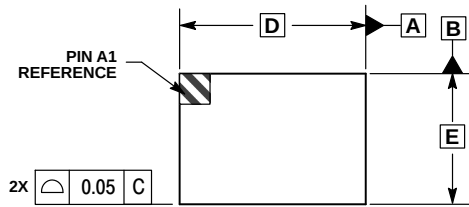




SCALE 4:1

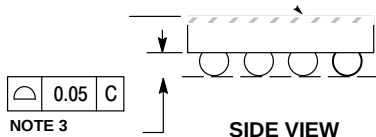
WLCSP11, 2.05x1.44
CASE 567BN
ISSUE O

DATE 26 JUL 2010



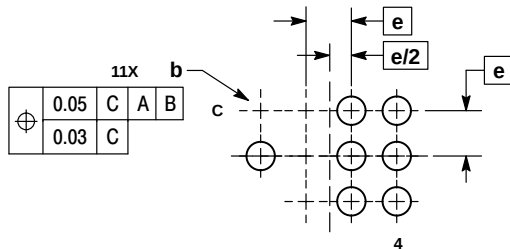
TOP VIEW

OptiGuard Option



SIDE VIEW

SEATING
PLANE



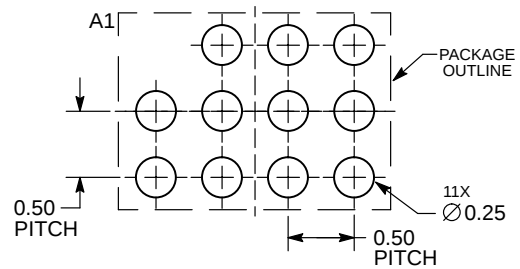
BOTTOM VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.56	0.72
A1		
A2	0.42	REF
b	0.29	0.35
D	2.05	BSC
E		
e	0.50	BSC

**RECOMMENDED
SOLDERING FOOTPRINT***



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

DOCUMENT NUMBER: 98AON49822E

DESCRIPTION: WLCSP11, 2.05X1.44

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